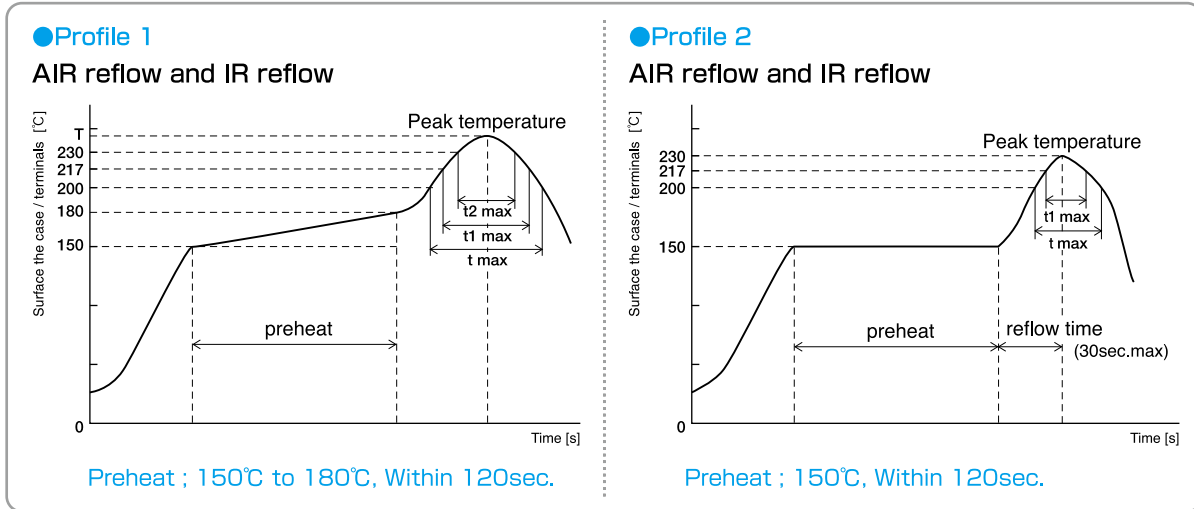


Soldering Condition / Reflow Soldering Condition

■ Soldering Condition

- Soldering with a soldering iron : within 350°C×3 seconds unless otherwise specified in the spec.
- Flow soldering : within 260°C×10 seconds unless otherwise specified in the spec.
(Do not apply flow soldering to SMD type.)
- Thermal curing oven : ambient temperature within 150°C×2 minutes.

■ Reflow Soldering Condition



Series	Voltage (V)	Size	Time for more than 200°C (t)	Time for more than 217°C (t1)	Time for more than 230°C (t2)	Peak temperature Within 5sec.(T)	Profile
CE-BS, CE-BSS CE-FS, CE-FSS CE-FH, CE-GA CE-AX, CE-KX CE-ZC, CE-LH CE-LL, CE-NP CE-FN	4 to 63	φ4 to φ6.3	Within 70sec.	Within 60sec.	Within 40sec.	250°C	1
		φ8	Within 60sec.	Within 50sec.	Within 30sec.	245°C	1
		φ10, φ12.5	Within 50sec.	Within 40sec.	Within 20sec.	240°C	1
		φ16, φ18	Within 50sec.	Within 30sec.	Within 15sec.	235°C	1
	80 to 100	φ4 to φ6.3	Within 60sec.	Within 50sec.	Within 40sec.	250°C	1
		φ8	Within 60sec.	Within 40sec.	Within 30sec.	240°C	1
		φ10	Within 50sec.	Within 30sec.	Within 20sec.	240°C	1
		φ12.5	Within 50sec.	Within 30sec.	Within 20sec.	235°C	1
	160 to 400	φ16, φ18	Within 45sec.	Within 20sec.	Within 10sec.	235°C	1
		φ8, φ10	Within 50sec.	Within 30sec.	Within 20sec.	240°C	1
		φ12.5	Within 45sec.	Within 20sec.	Within 10sec.	235°C	1
		φ16, φ18	Within 30sec.	Within 15sec.	—	230°C	2
CE-FU, CE-ZX CE-LX, CE-LS CE-PC, CE-PH CE-PS, CE-PF CE-TH	6.3 to 50	φ4 to φ8	Within 80sec.	Within 70sec.	Within 40sec.	260°C	1
		φ10×10.2 to 13.5	Within 70sec.	Within 60sec.	Within 40sec.	250°C	1
		φ12.5	Within 60sec.	Within 50sec.	Within 30sec.	245°C	1
		φ10×7.7, φ16, φ18	Within 50sec.	Within 40sec.	Within 20sec.	240°C	1
	63	φ6.3	Within 70sec.	Within 60sec.	Within 40sec.	250°C	1
		φ8	Within 60sec.	Within 50sec.	Within 30sec.	245°C	1
		φ10, φ12.5	Within 50sec.	Within 40sec.	Within 20sec.	240°C	1
		φ16, φ18	Within 50sec.	Within 40sec.	Within 15sec.	235°C	1
	80 to 100	φ8	Within 60sec.	Within 50sec.	Within 30sec.	240°C	1
		φ10	Within 50sec.	Within 40sec.	Within 20sec.	240°C	1
		φ12.5	Within 50sec.	Within 40sec.	Within 20sec.	235°C	1
		φ16, φ18	Within 45sec.	Within 30sec.	Within 10sec.	235°C	1
CE-BD, CE-FD, CE-LD	ALL	ALL	Within 60sec.	Within 50sec.	Within 30sec.	245°C	1
CE-BE, CE-FE	ALL	ALL	Within 50sec.	Within 40sec.	Within 20sec.	240°C	1

The maximum cycle of reflow soldering is two times. The second cycle must be done after sufficient cooling time for more than one hour to return the temperatures of circuit boards and components back to room temperature. Please refer to page 20 for reflow soldering condition of EP-cap.